

DERWENT-ACC-NO: 1995-010440

DERWENT-WEEK: 199502

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TITLE: Semiconductor manufacturing device
for connecting by a wiring board and semiconductor
element - incorporates rollers to roll film which provides
even pressure on electric conductor wiring and
semiconductor element by pressurisation jig

PATENT-ASSIGNEE: MATSUSHITA ELECTRONICS CORP [MATE]

PRIORITY-DATA: 1993JP-0082019 (April 8, 1993)

PATENT-FAMILY:

PUB-NO	PAGES	PUB-DATE	MAIN-IPC	
LANGUAGE				
JP 06295940 A	004	October 21, 1994	H01L 021/60	N/A

APPLICATION-DATA:

PUB-NO	APPL-DESCRIPTOR	APPL-NO
APPL-DATE		
JP 06295940A 1993JP-0082019	N/A April 8, 1993	

INT-CL (IPC): H01L021/60

ABSTRACTED-PUB-NO: JP 06295940A

BASIC-ABSTRACT:

The semiconductor manufacturing device sets the position of electric conductor wiring (2) and electrode (4) of semiconductor element (3) over the substrate (1). On setting the position, an adhesive agent (23) is used to connect the wiring with that of the semiconductor element by applying